RELIABILITY REPORT
FOR
MAX238CWG+
PLASTIC ENCAPSULATED DEVICES

September 9, 2009

MAXIM INTEGRATED PRODUCTS
120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
Ken Wendel
Quality Assurance
Director, Reliability Engineering
Conclusion

The MAX238CWG+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim’s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim’s quality and reliability standards.

Table of Contents

I. Device Description
   A. General

   The MAX220-MAX249 family of line drivers/receivers is intended for all EIA/TIA-232E and V.28/V.24 communications interfaces, particularly applications where ±12V is not available. These parts are especially useful in battery-powered systems, since their low-power shutdown mode reduces power dissipation to less than 5µW. The MAX225, MAX233, MAX235, and MAX245/MAX246/MAX247 use no external components and are recommended for applications where printed circuit board space is critical.
II. Manufacturing Information

A. Description/Function: +5V-Powered, Multichannel RS-232 Drivers/Receivers
B. Process: M6
C. Number of Device Transistors: 
D. Fabrication Location: Oregon
E. Assembly Location: Philippines, Malaysia
F. Date of Initial Production: Pre 1997

III. Packaging Information

A. Package Type: 24-pin SOIC (W)
B. Lead Frame: Copper
C. Lead Finish: 100% matte Tin
D. Die Attach: Conductive Epoxy
E. Bondwire: Gold (1.3 mil dia.)
F. Mold Material: Epoxy with silica filler
G. Assembly Diagram: #05-0701-0366
H. Flammability Rating: Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C: Level 1
J. Single Layer Theta Ja: 85°C/W
K. Single Layer Theta Jc: 18°C/W

IV. Die Information

A. Dimensions: 138 X 155 mils
B. Passivation: Si$_3$N$_4$/SiO$_2$ (Silicon nitride/ Silicon dioxide)
C. Interconnect: Al/1.0%Si
D. Backside Metallization: None
E. Minimum Metal Width: Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing: Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions: 5 mil. Sq.
H. Isolation Dielectric: SiO$_2$
I. Die Separation Method: Wafer Saw
V. Quality Assurance Information

A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)
   Bryan Preeshl (Managing Director of QA)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
   0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ($\lambda$) is calculated as follows:

\[
\frac{1}{\text{MTTF}} = \frac{6.21}{192 \times 4340 \times 2408 \times 2}
\]

(Chi square value for MTTF upper limit)

\[
\lambda = 1.51 \times 10^{-9}
\]

\[
\lambda = 1.51 \text{ F.I.T. (60% confidence level @ 25°C)}
\]

The following failure rate represents data collected from Maxim’s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the M6 Process results in a FIT Rate of 0.22 @ 25C and 3.73 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The PS29 die type has been found to have all pins able to withstand a HBM transient pulse of +/- 1500 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/- 100 mA.
**Table 1**  
Reliability Evaluation Test Results

**MAX238CWG+**

<table>
<thead>
<tr>
<th>TEST ITEM</th>
<th>TEST CONDITION</th>
<th>FAILURE IDENTIFICATION</th>
<th>SAMPLE SIZE</th>
<th>NUMBER OF FAILURES</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Static Life Test</strong> (Note 1)</td>
<td>Ta = 135°C Biased Time = 192 hrs.</td>
<td>DC Parameters &amp; functionality</td>
<td>2408</td>
<td>2</td>
</tr>
<tr>
<td><strong>Moisture Testing</strong> (Note 2)</td>
<td>HAST Ta = 130°C RH = 85% Biased Time = 96hrs.</td>
<td>DC Parameters &amp; functionality</td>
<td>77</td>
<td>0</td>
</tr>
<tr>
<td><strong>Mechanical Stress</strong> (Note 2)</td>
<td>Temperature -65°C/150°C Cycle 1000 Cycles Method 1010</td>
<td>DC Parameters &amp; functionality</td>
<td>77</td>
<td>0</td>
</tr>
</tbody>
</table>

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data